

Features

- Micropower consumption for battery powered applications
- Omnipolar, output switches with absolute value of North or South pole from magnet
- Operation down to 2.5V
- High sensitivity for direct reed switch replacement applications



General Description

The SS3212Omnipolar Hall effect sensor IC is fabricated from mixed signal CMOS technology .It incorporates advanced chopper-stabilization techniques to provide accurate and stable magnetic switch points.

The circuit design provides an internally controlled clocking mechanism to cycle power to the Hall element and analog signal processing circuits. This serves to place the high current-consuming portions of the circuit into a "Sleep" mode. Periodically the device is "Awakened" by this internal logic and the magnetic flux from the Hall element is evaluated against the predefined thresholds. If the flux density is above or below the Bop/Brp thresholds then the output transistor is driven to change states accordingly. While in the "Sleep" cycle the output transistor is latched in its previous state. The design has been optimized for service in applications requiring extended operating lifetime in battery powered systems. The output transistor of the SS3212 will be latched on (Bop) in the presence of a sufficiently strong South or North magnetic

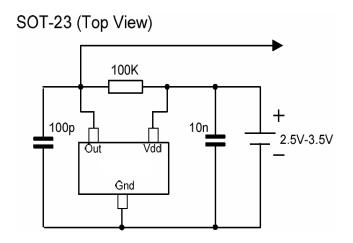
field facing the marked side of the package. The output will be latched off (Brp) in the absence of a magnetic field.

Applications

- Solid state switch
- Handheld Wireless Handset Awake Switch
- Lid close sensor for battery powered devices
- Magnet proximity sensor for reed switch replacement in low duty cycle applications



Typical Application Circuit



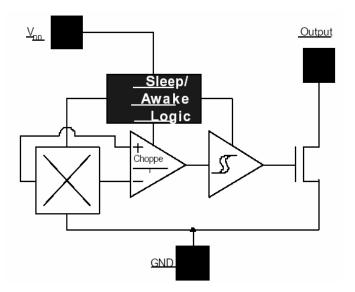
SEC's pole-independent sensing technique allows for operation with either a north pole or south pole magnet orientation, enhancing the manufacturability of the device. The

state-of-the-art technology provides the same output polarity for either pole face.

It is strongly recommended that an external bypass capacitor be

connected (in close proximity to the Hall sensor) between the supply and ground of the device to reduce both external noise and noise generated by the chopper-stabilization technique. This is especially true due to the relatively high impedance of battery supplies.

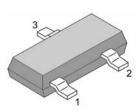
Functional Block Diagram

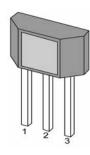




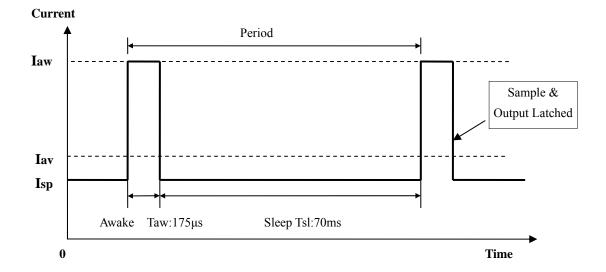
Pins Definition and Description

SOT Pin №	SIP Pin №	Name	Туре	Function
1	1	VDD	Supply	Supply Voltage pin
2	3	OUT	Output	Open Drain Output pin
3	2	GND	Ground	Ground pin





Internal Timing Circuit





Absolute Maximum Ratings

Parameter	Symbol	Value	Units
Supply Voltage(operating)	V _{DD}	6	V
Supply Current	I _{DD}	5	mA
Output Voltage	V _{OUT}	6	V
Output Curent	I _{OUT}	5	mA
Operating Temperature Range	T _A	-40 to 85	С
Storage Temperature Rang	Τs	-50 to 150	С
ESD Sensitivity	-	4000	V

Exceeding the absolute maximum ratings may cause permanent damage. Exposure to absolute-maximum rated conditions for extended periods may affect device reliability.

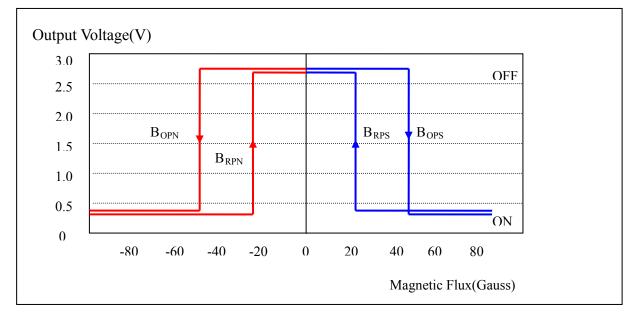
DC Electrical Characteristics

DC Operating Parameters: $T_A = 25^{\circ}C$, $V_{DD}=2.75V$.

Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Operating voltage	V_{DD}	Operating	2.5	3	5.5	V
Supply current	I _{DD}	Average		5		μΑ
Output Current	I _{OUT}				1.0	mA
Saturation Voltage	V _{SAT}	I _{OUT} =1mA			0.4	V
Awake mode time	T_{AW}	Operating		175		μS
Sleep mode time	T _{SL}	Operating			70	mS



Magnetic Characteristics



Operating Parameters: $T_A = 25^{\circ}C$, $V_{DD}=2.75V_{DC}$.

PARAMETER	Symbol	Min	Туре	Max	Units
Operating Point	Вор	-	+/-35	+/-60	Gs
Release Point	Brp	+/-5	+/-21	-	Gs
Hysteresis	Bhys	-	14	-	Gs

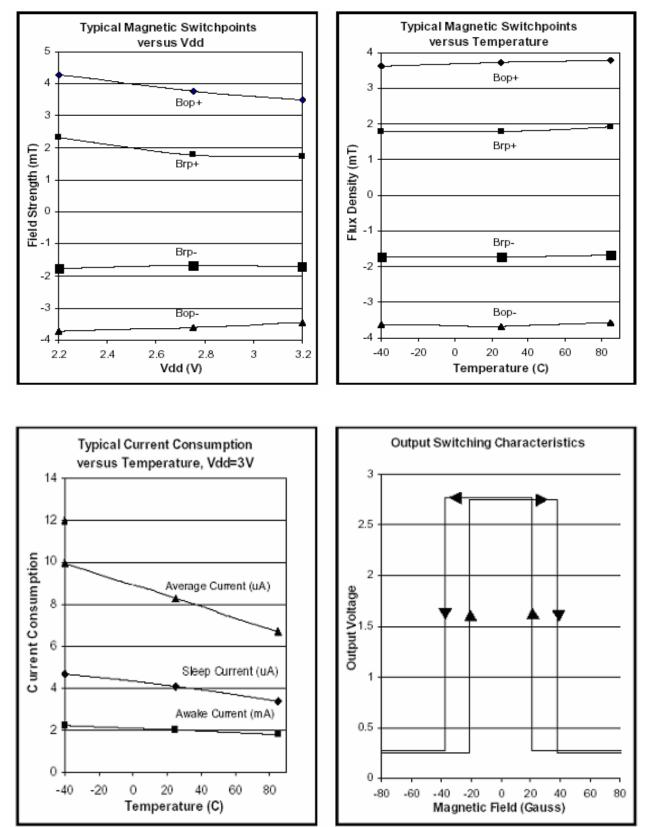
ESD Protection

Human Body Model (HBM) tests according to: Mil. Std. 883F method 3015.7

Parameter	Symbol	Limit		Unit	Notes
r al ameter	Symbol	Min	Max	Umt	Notes
ESD Voltage	V _{ESD}		±4	kV	



Performance Characteristics





Unique Features

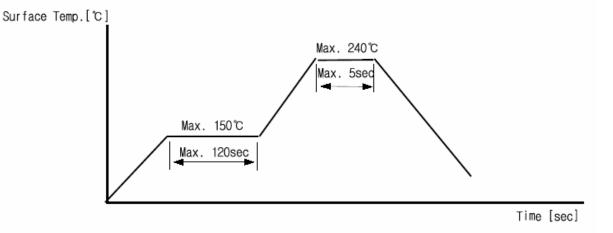
CMOS Hall IC Technology

The chopper stabilized amplifier uses switched capacitor techniques to eliminate the amplifier offset voltage, which, in bipolar devices, is a major source of temperature sensitive drift. CMOS makes this advanced technique possible. The CMOS chip is also much smaller than a bipolar chip, allowing very sophisticated circuitry to be placed in less space. The small chip size also contributes to lower physical stress and less power consumption.

Installation Comments

Consider temperature coefficients of Hall IC and magnetics, as well as air gap and life time variations. Observe temperature limits during wave soldering. Typical IR solder-reflow profile:

- No Rapid Heating and Cooling.
- Recommended Preheating for max. 2minutes at 150°C
- Recommended Reflowing for max. 5seconds at 240°C



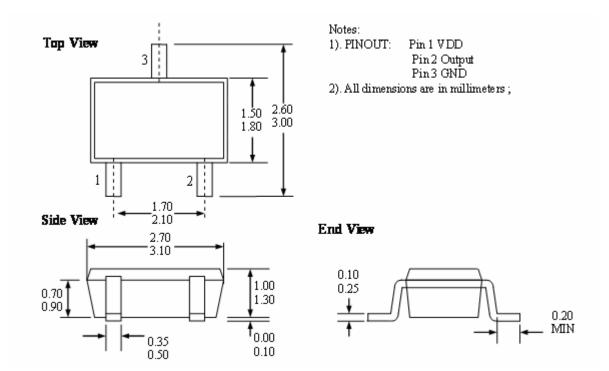
ESD Precautions

Electronic semiconductor products are sensitive to Electro Static Discharge (ESD). Always observe Electro Static Discharge control procedures whenever handling semiconductor products.

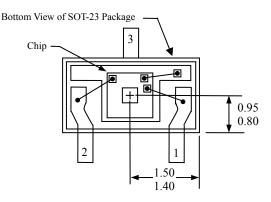


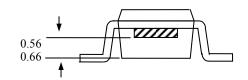
Package Information

Package LH, 3-Pin SOT-23:



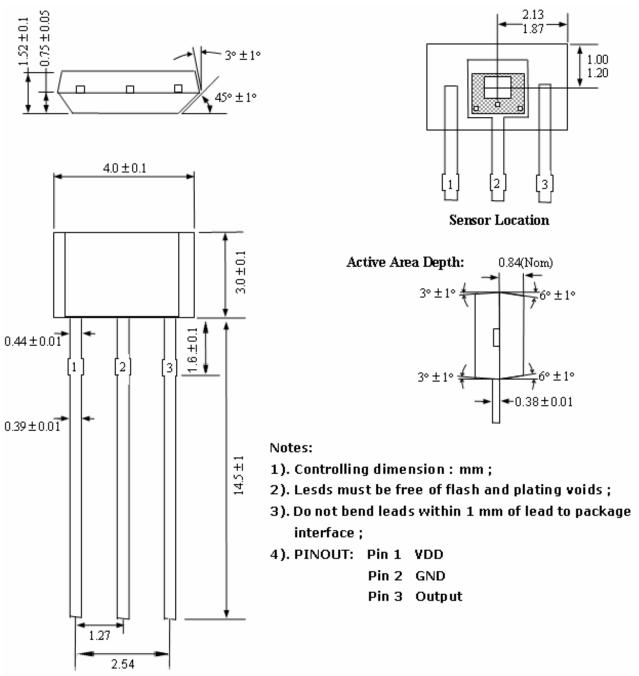
SOT-23 Package Hall Location







Package UA, 3-Pin SIP:





Ordering Information

Part No.	Pb-free	Temperature Code	Package Code	Packing
SS3212ESOT	YES	-40°C to 85°C	SOT-23	7-in. reel, 3000 pieces/reel
SS3212EUA	YES	-40°C to 85°C	TO-92	Bulk, 1000 pieces/bag
SS3212KSOT	YES	-40°C to 125°C	SOT-23	7-in. reel, 3000 pieces/reel
SS3212KUA	YES	-40°C to 125°C	TO-92	Bulk, 1000 pieces/bag
SS3212LSOT	YES	-40°C to 150°C	SOT-23	7-in. reel, 3000 pieces/reel
SS3212LUA	YES	-40°C to 150°C	TO-92	Bulk, 1000 pieces/bag